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(12) **United States Design Patent**
Yang

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(54) **INTEGRATED CIRCUIT PACKAGE**

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(30) **Foreign Application Priority Data**

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(51) **LOC (13) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**

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CPC H01L 27/00; H01L 27/01; H01L 27/013; H01L 27/016; H01L 27/02; H01L 27/0203; H01L 27/0207; H01L 27/04; H01L 27/06; H01L 27/0605; H01L 27/07; H01L 27/08; H01L 27/14618; H01L 21/4846; H01L 21/4853; H01L 21/4857; H01L 21/56; H01L 21/561; H01L 21/563; H01L 21/565; H01L 21/566; H01L 21/568; H01L 23/498; H01L 23/49805; H01L 23/3114; H01L 23/3121; H01L 23/3107; H01L 23/481; H01L 23/5384; H01L 23/528; H01L 33/48; H01L 33/52; H01L 33/54; H01L 33/62; H01L 24/02; H01L 24/97; H01L 31/0203; H01L 25/105

See application file for complete search history.

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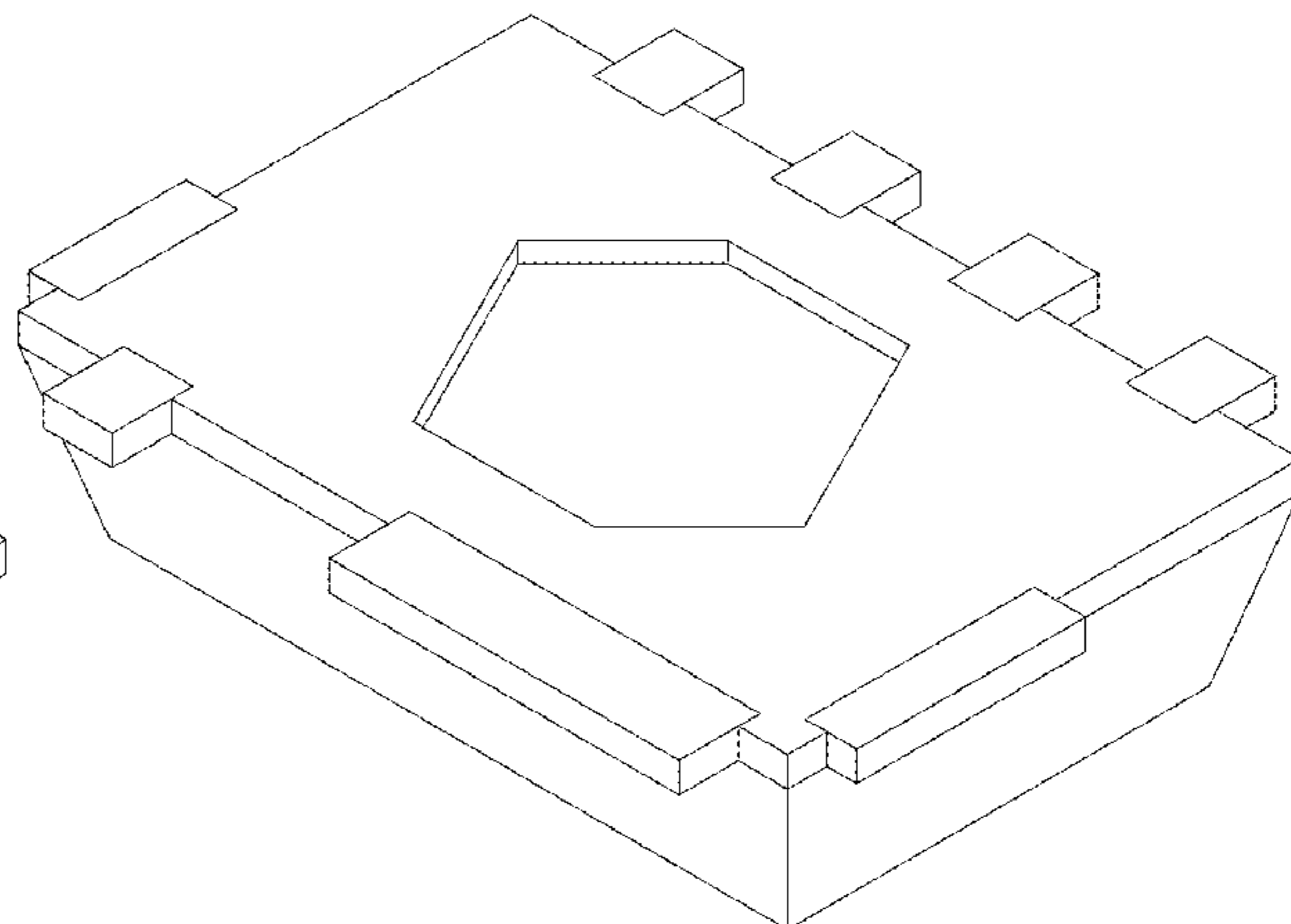
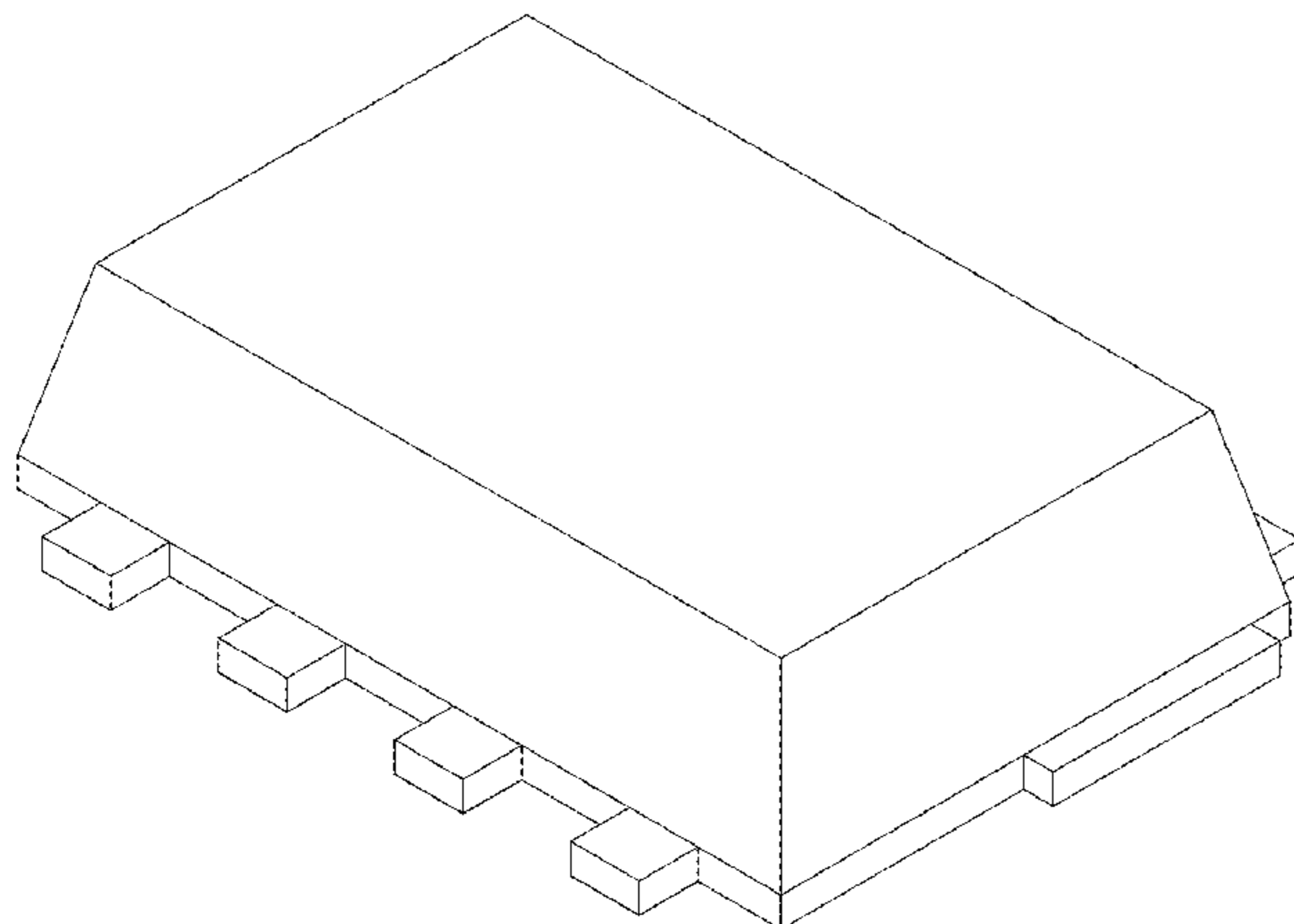
(57) **CLAIM**

The ornamental design for an integrated circuit package, as shown.

DESCRIPTION

FIG. 1 is a front elevational view of an integrated circuit package showing my new design;
FIG. 2 is a rear elevational view thereof;
FIG. 3 is a left side elevational view thereof;
FIG. 4 is a right side elevational view thereof;
FIG. 5 is a top plan view thereof;
FIG. 6 is a bottom plan view thereof;
FIG. 7 is a front perspective view thereof; and,
FIG. 8 is a rear perspective view thereof.

1 Claim, 8 Drawing Sheets



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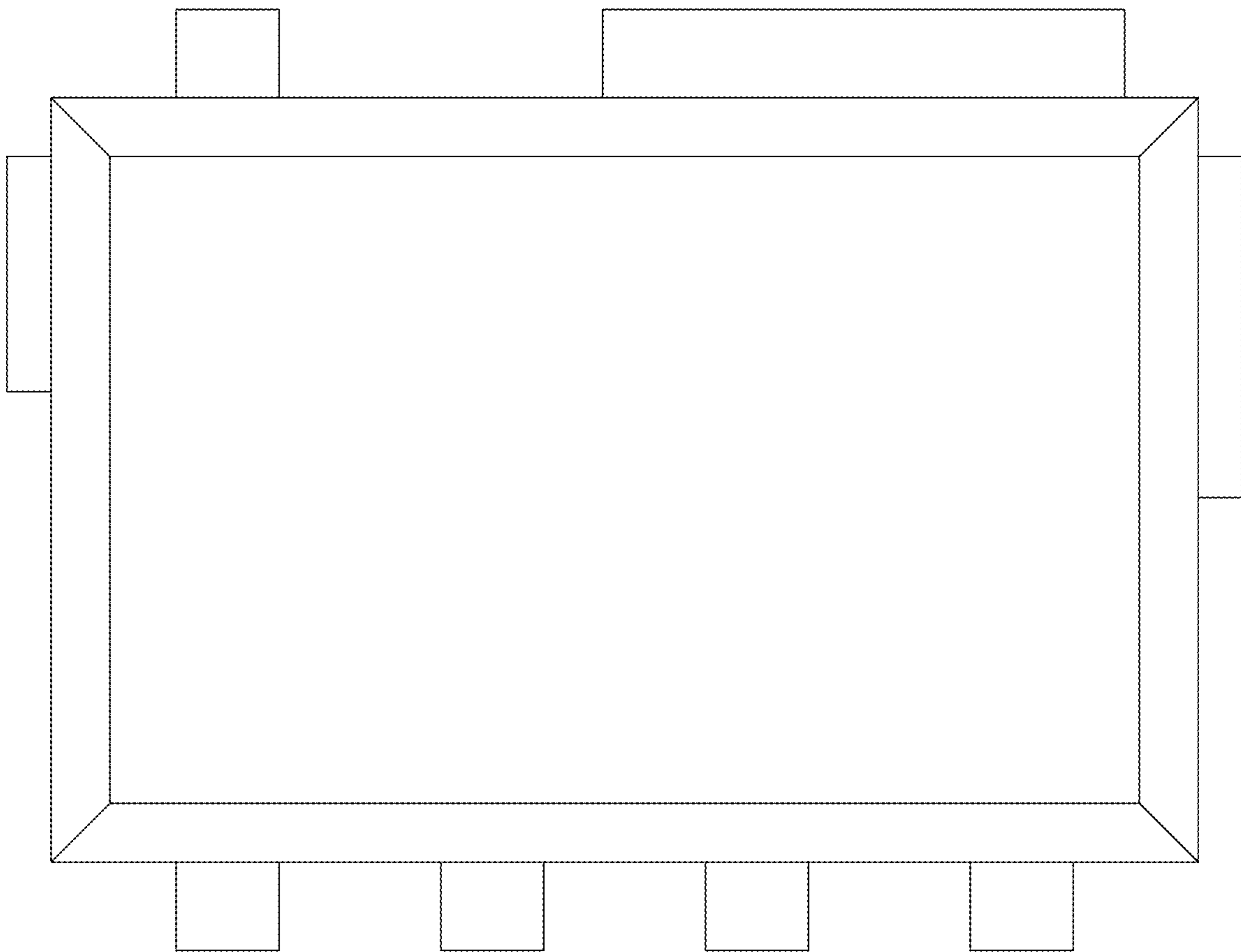


Fig. 1

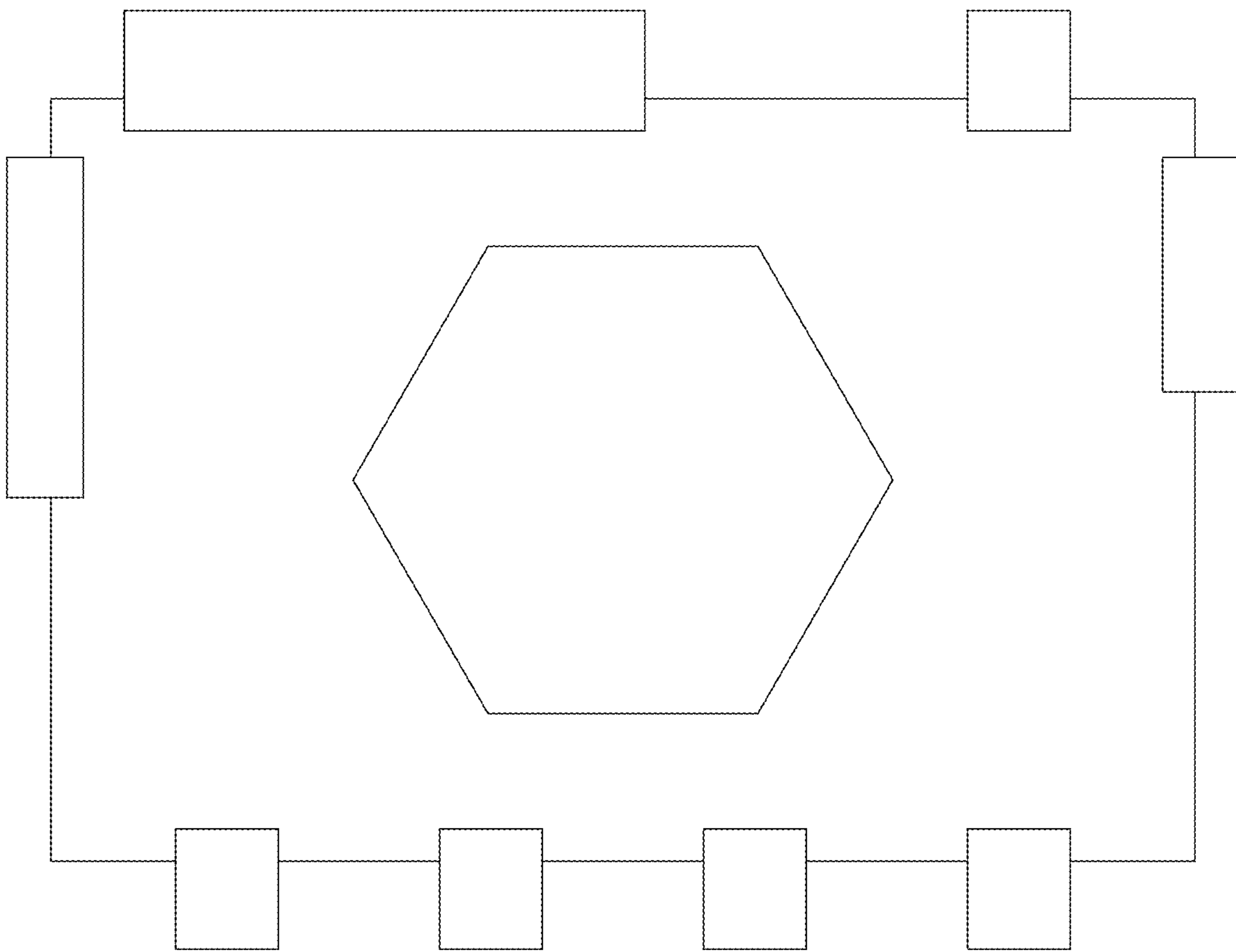


Fig. 2

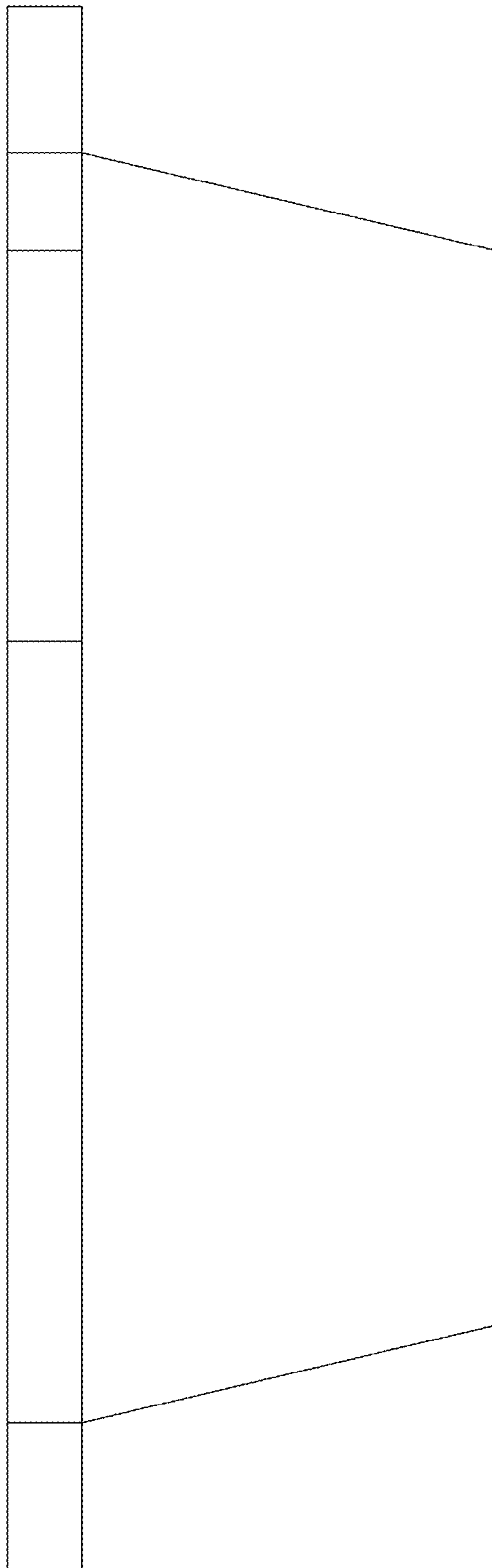


Fig. 3

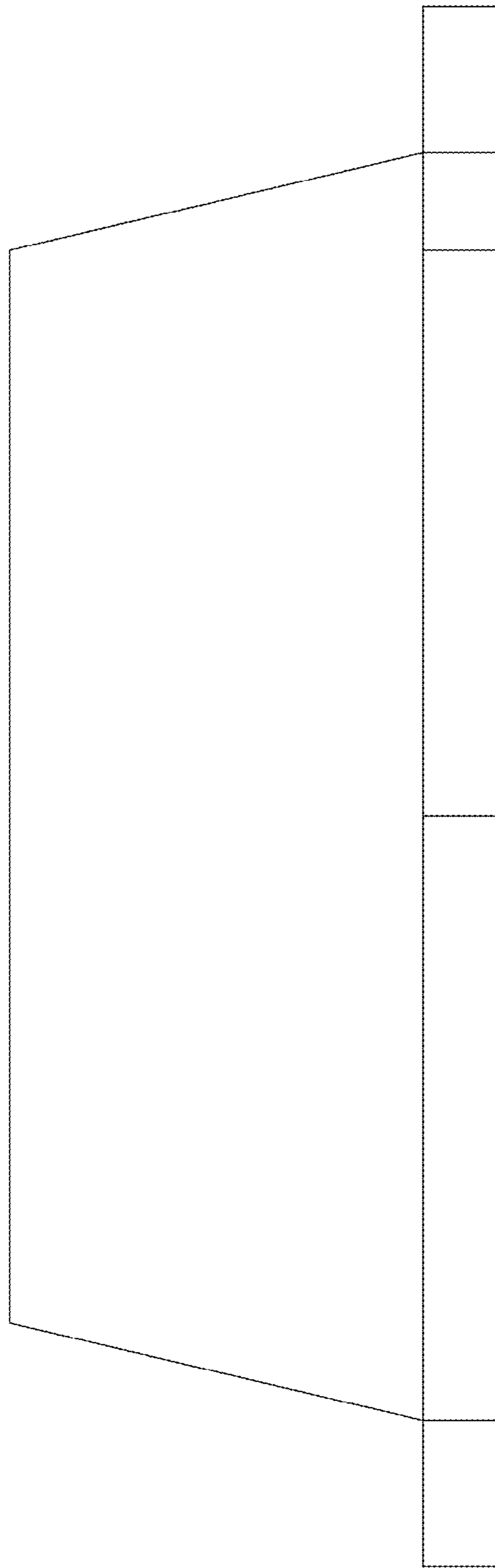


Fig. 4

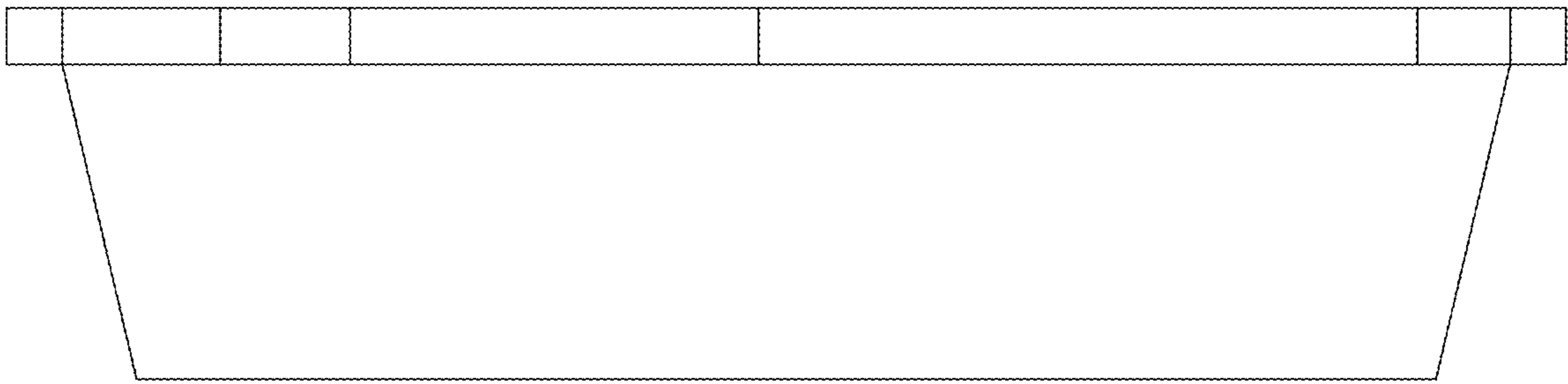


Fig. 5

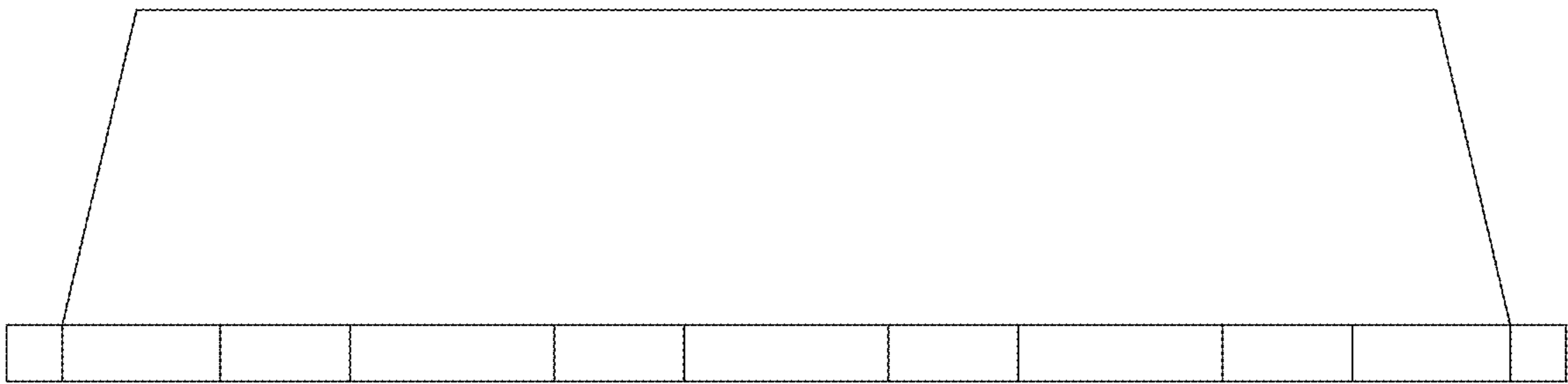


Fig. 6

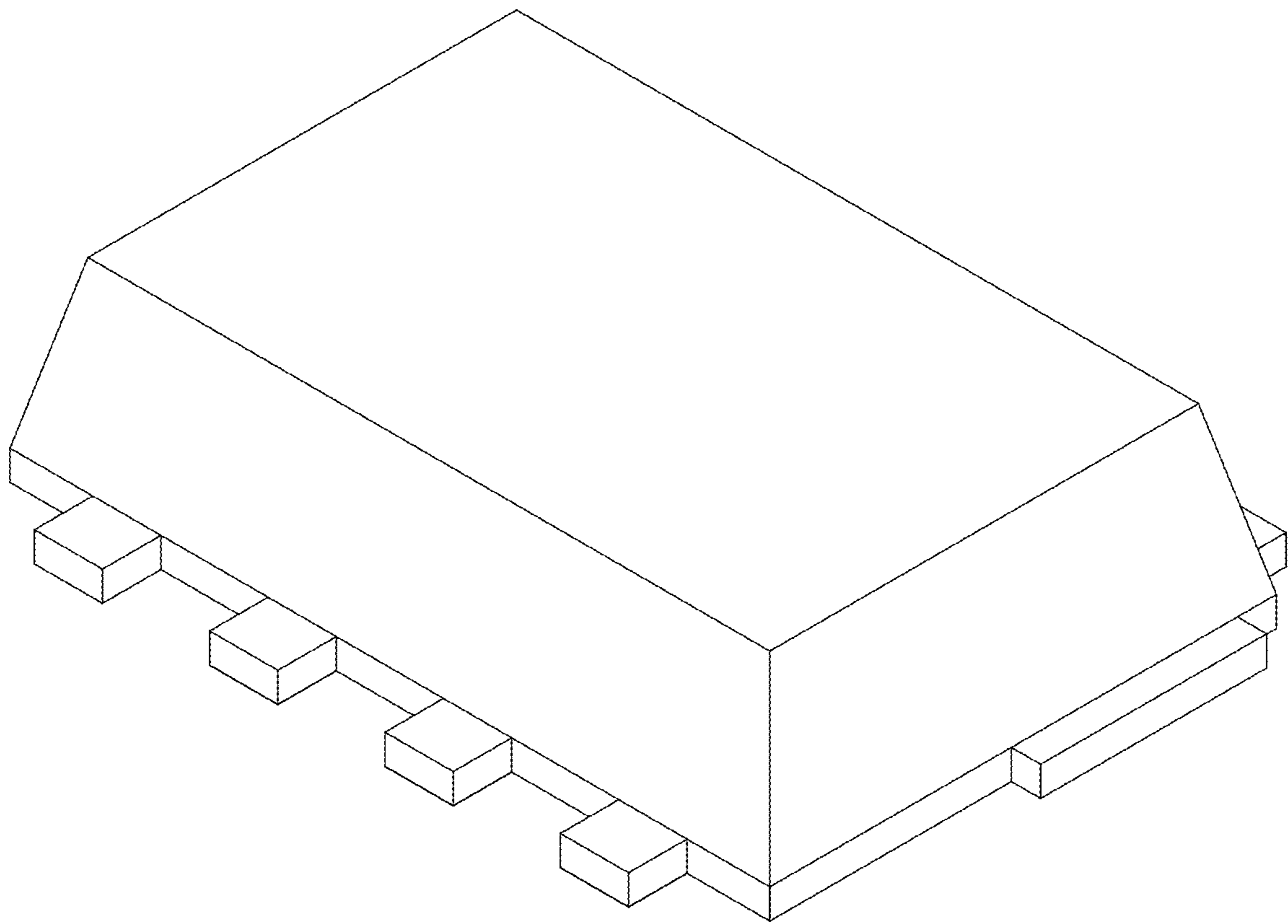


Fig. 7

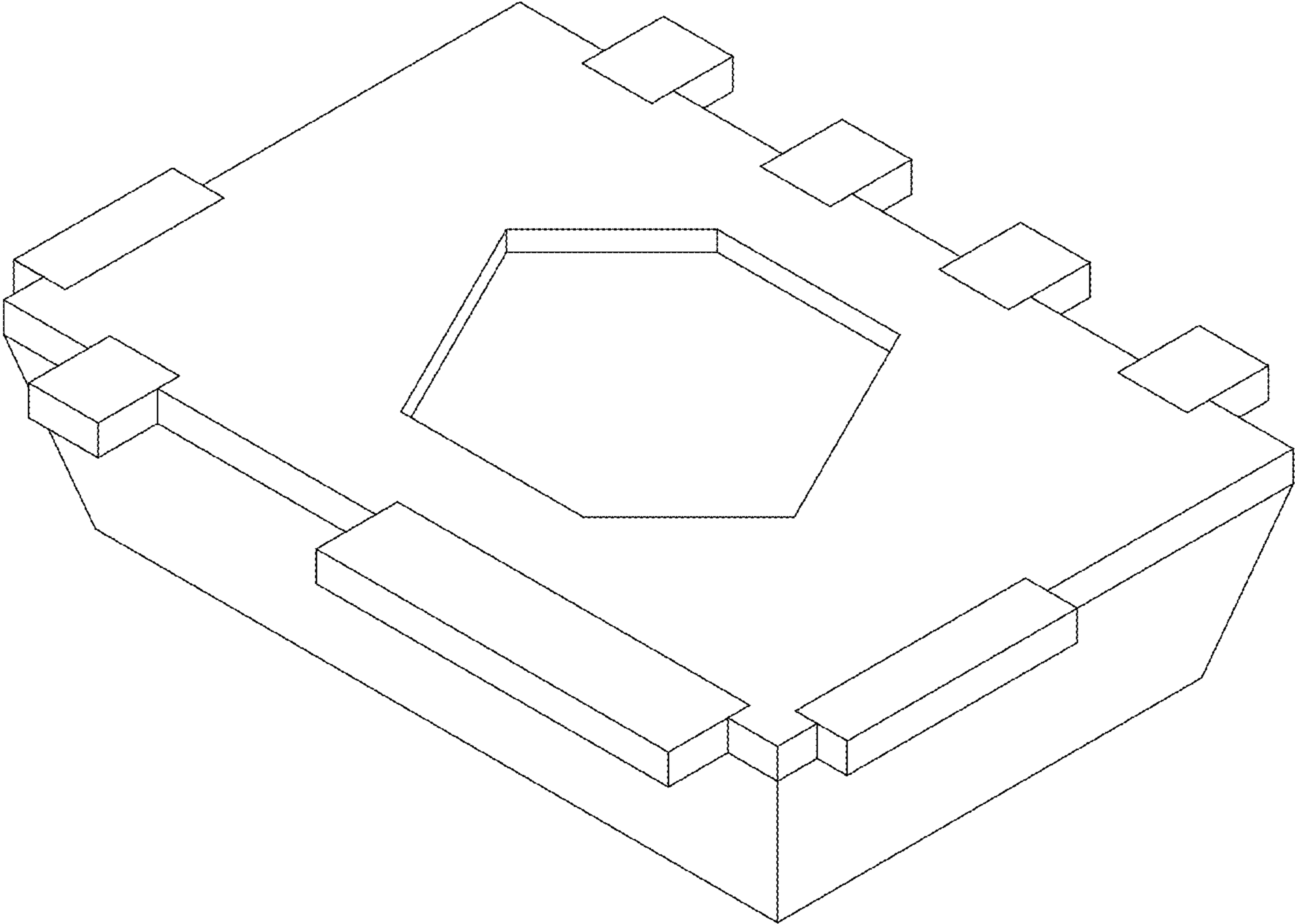


Fig. 8